

BRAD6265DSC

Rev.A Mar.-2022



DATA SHEET

/ Descriptions

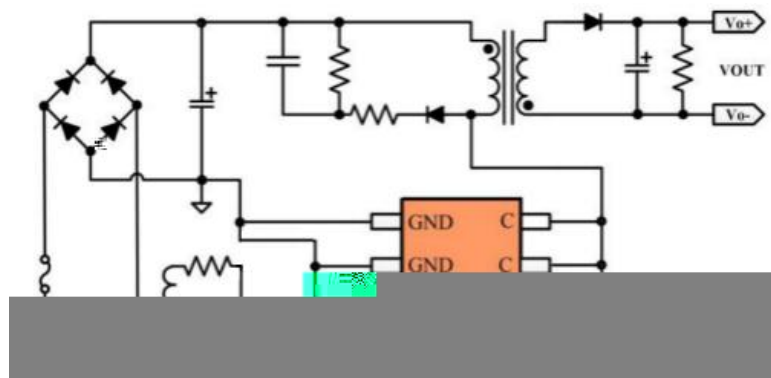
/ Features

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/ Applications

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- ◆
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- ◆

/ Application Circuit





Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
	T_{LEB}			300		ns
	$I_{P_{MAX}}$		300	330	360	mA
FB						
	V_{FB_REF}			1.2		V

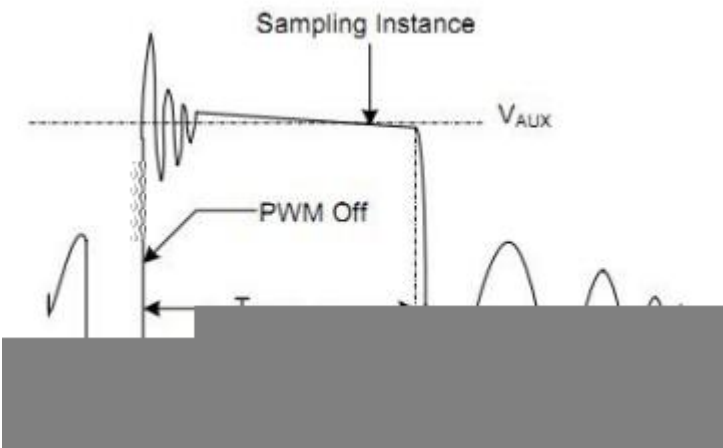
V

/ Functional Description

BRAD6265DSC		PWM
	BRAD6265DSC	
	CC/CV	
90V~264V		TL431
/		
BRAD6265DSC	CC	
	CV	FB
FB		
	BRAD6265DSC	DCM
	CC/CV	I _p

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FB

GND

K L M NO P Q R S T U V W X Y X

Z [V W \]

^ _ ` a FB b c d e f \]

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[o p \] Vo.

q r s \] t u v w x

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FB

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/ Functional Description

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 y U V L O z VCC Å å Č ý y O T P z ć Ć Ć é ê y O C P z \] Ć ý î
 ĭ ð ñ ÷ È ì Č ċ VCC ± ² ¶ ` Ď đ Č » VCC Đ đ đ Ě Ê þ Ě °
 X ě Ě X Z Ò ò ù ú ě È đ ü õ T U

PCB

Í t BRAD6265DSC PCB è Ě ģ Ě ² M ě x
 GND Ğ ğ PCB Ğ ş x Ě ì CS ù ú ß ç ğ ě | GND Ğ \ đ ğ Ğ PCB Ğ ş
 è ğ Ğ Ć Ĥ ĥ ĥ Ĥ đ \ đ ğ R Þ
 VCC ğ x ĥ Ĩ Ĩ ` 2.2uF Ĩ ì X 7 R Ĩ Ĩ ğ Ĩ ≥ 6.3V | Ĩ ³ Đ Ĩ ğ 4.7uF/10V VCC
 ğ è Ě l Ĩ Ě ì VCC GND Ğ ğ, Ě ì VCC Ğ ğ Ĩ Ĩ Ĩ ª | Ğ ş Ĩ ğ ě Ķ l Ě ì VCC Ğ ğ Ķ Ķ
 Ú Ĺ Þ
 FB Ğ ğ x Ĥ FB Í Ľ Ĩ | FB Ğ ğ í Ľ Ĩ Ě Ľ Ĩ ° K ě ì È Ĩ ^
 _ ` Ł è ł Ń | Ń ¥ Ń Ĩ Ě ģ Þ
 C Ğ ğ x Ń » Ń ĥ C Ğ ğ Đ ģ Ō õ ² đ Ĩ Ě ì Ō õ Ū Ō;
 ¿ ´ n õ ş x Æ æ ¿ ´ n Ō õ Ř ° K Ý C Ý ř ş ğ n Ō õ ² Ř ° K Ý W
 « ¬ Y Ý \] ğ n Ō õ EMI ř Ř ř × Ø
 Š R S š ° x ä ` Š š K Ş ş c Š VCC ğ q š k è VCC š k š p í VCC > 3.3V
 Š R S ° Ţ Ţ Ţ Ě ģ

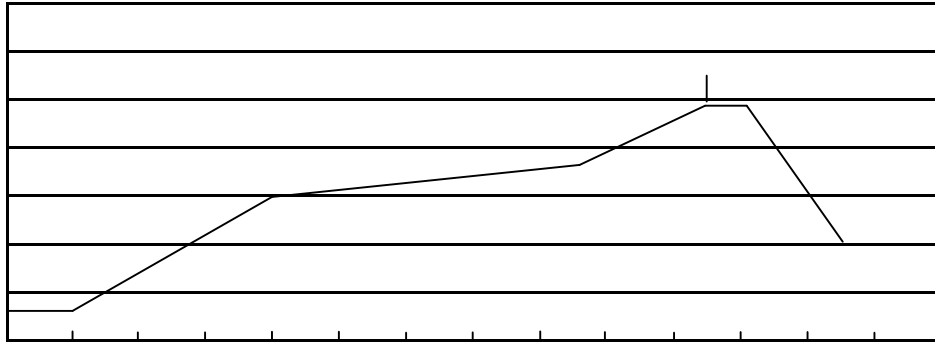
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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | |
|---|-------------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366

/ Notices